



Material Content Data Sheet



Sales Product Name		ESD201-B2-03LRH E6327		Issued		29. August 2013		
MA#		MA001010440						
Package		PG-TSLP-3-9		Weight*		0.62 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.020	3.21	3.21	32118	32118
leadframe	non noble metal	nickel	7440-02-0	0.131	21.03	21.03	210260	210260
wire	noble metal	gold	7440-57-5	0.009	1.40	1.40	14047	14047
encapsulation	organic material	carbon black	1333-86-4	0.003	0.47		4726	
	plastics	epoxy resin	-	0.040	6.38		63786	
	inorganic material	silicondioxide	60676-86-0	0.252	40.40	47.25	403983	472495
leadfinish	noble metal	gold	7440-57-5	0.011	1.70	1.70	17002	17002
plating	noble metal	silver	7440-22-4	0.017	2.78	2.78	27763	27763
solder	non noble metal	tin	7440-31-5	0.029	4.64		46394	
	noble metal	gold	7440-57-5	0.112	17.99	22.63	179921	226315
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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